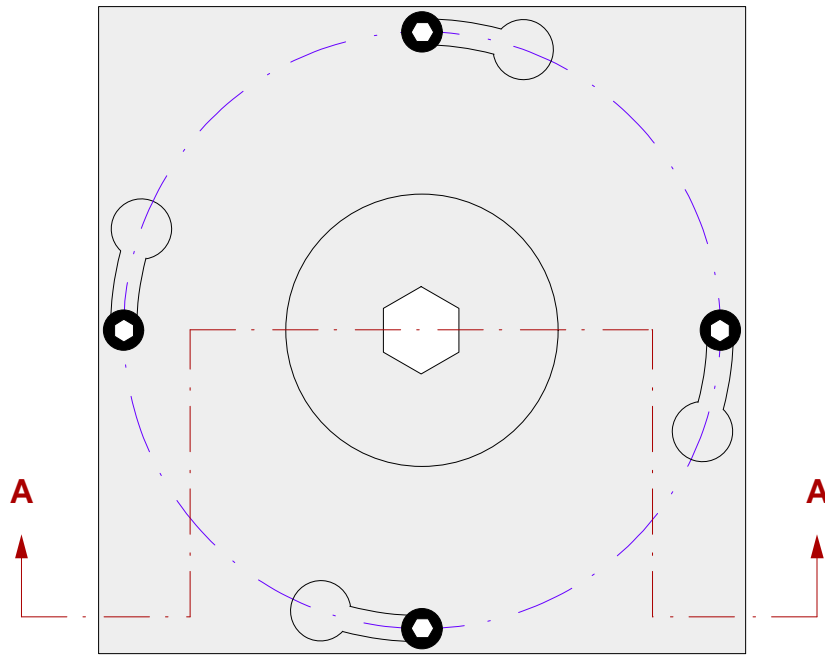


GHz BGA Socket - Direct mount, solderless

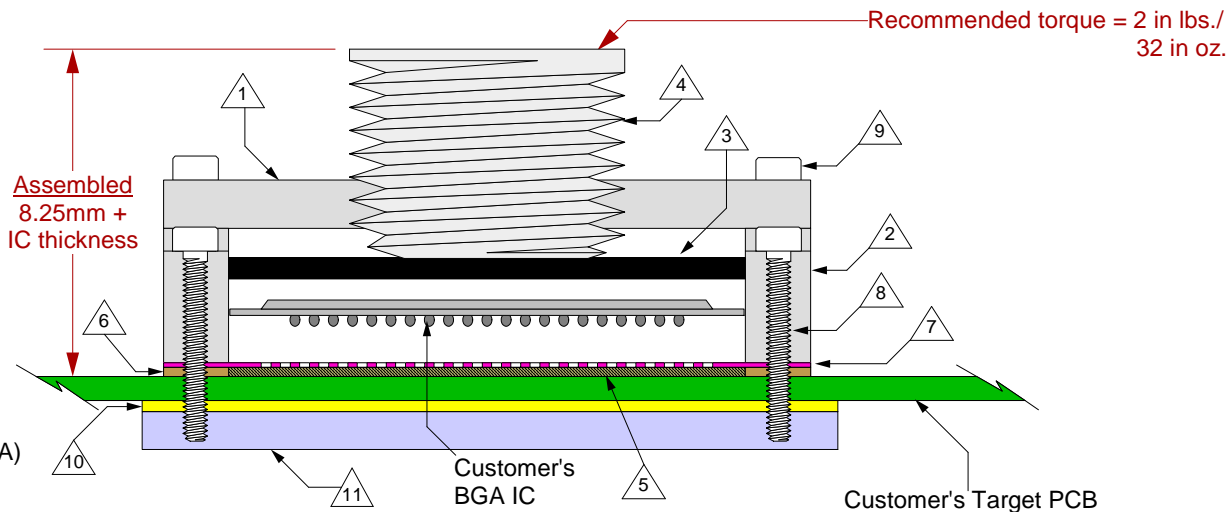
Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid

Top View



Side View
(Section AA)



- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- △ 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-7067 Drawing

Status: Released

Scale: -

Rev: C

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Tele: (952) 229-8200
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Drawing: H. Hansen

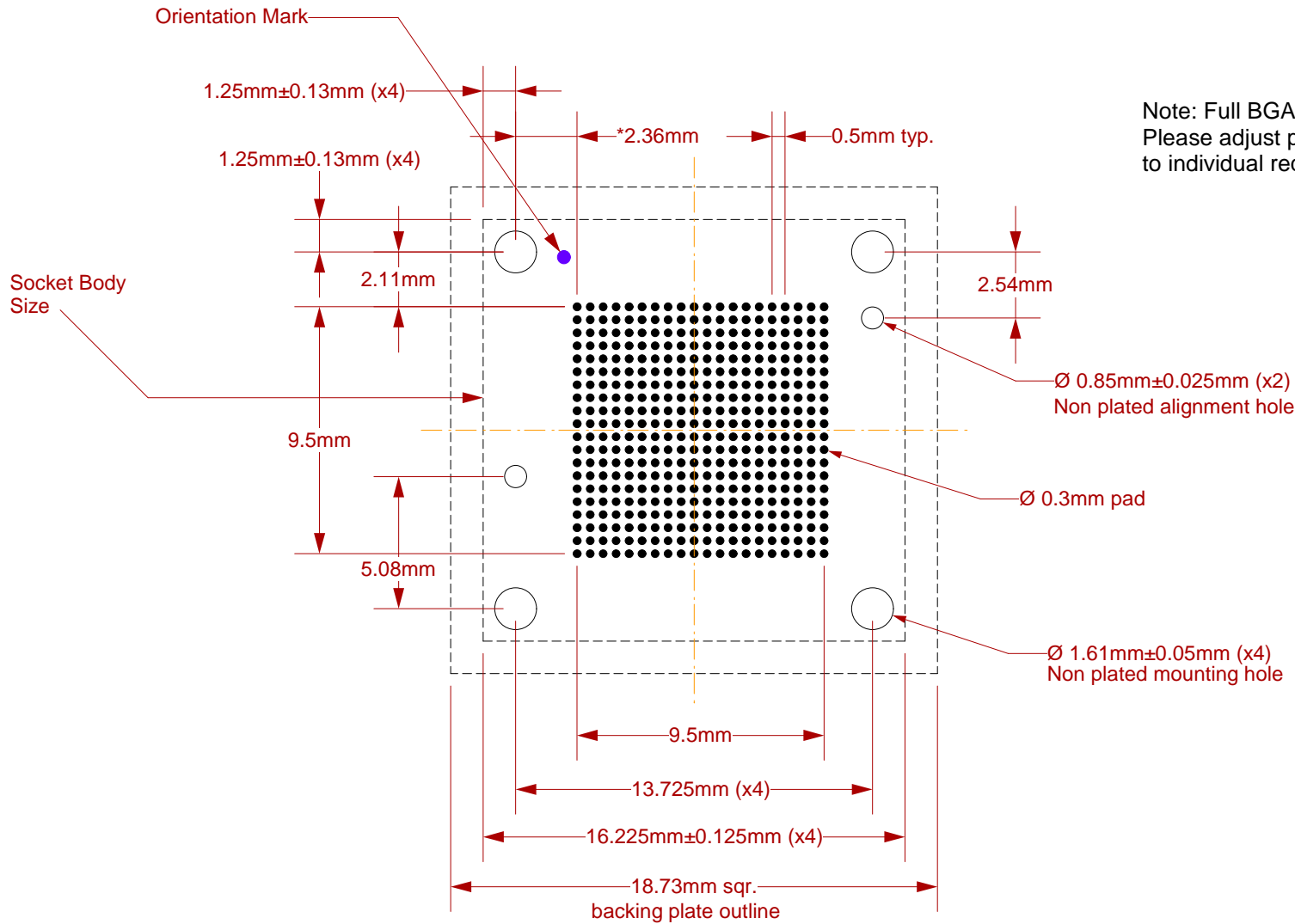
Date: 6/17/05

File: SG-BGA-7067 Dwg

Modified: 7/7/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Note: Full BGA pattern shown. Please adjust pattern according to individual requirements.

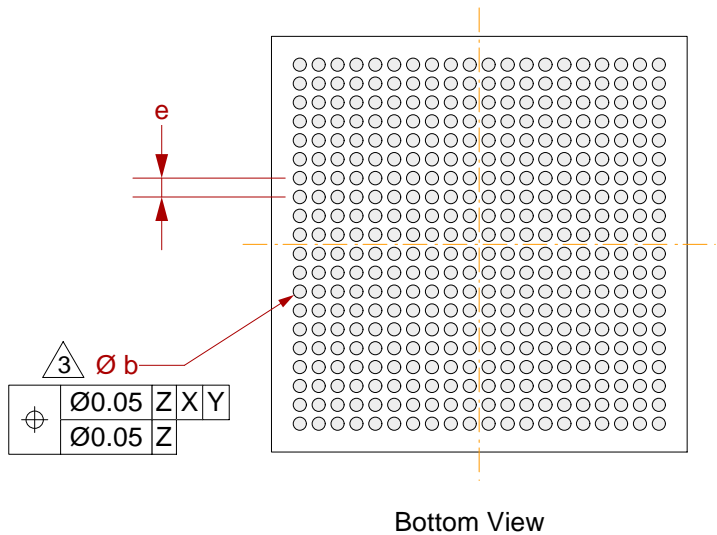
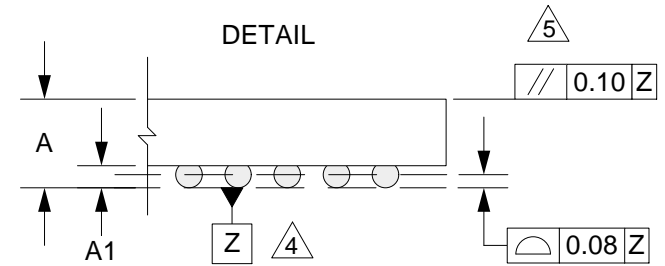
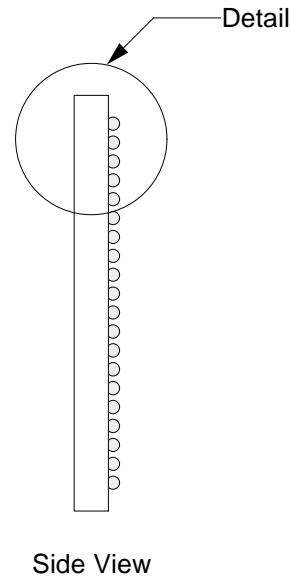
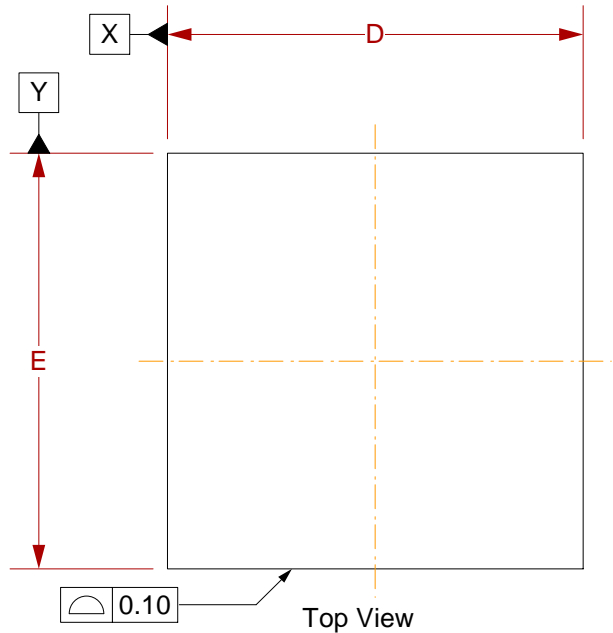
Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


	SG-BGA-7067 Drawing	Status: Released	Scale: 4:1	Rev: C
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		File: SG-BGA-7067 Dwg		Modified: 7/7/09, AE



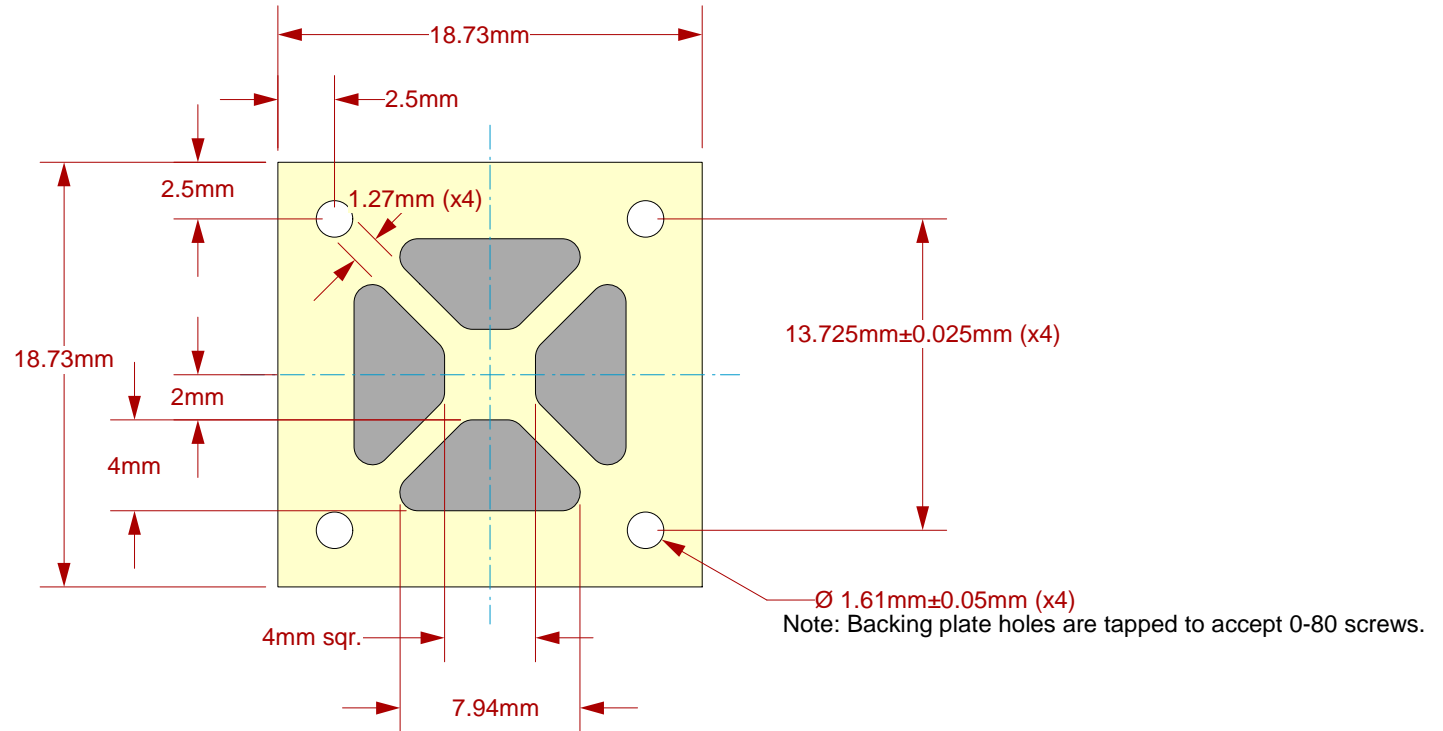
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.4
A1	0.2	0.3
b		0.35
D	11.0 BSC	
E	11.0 BSC	
e	0.5 BSC	

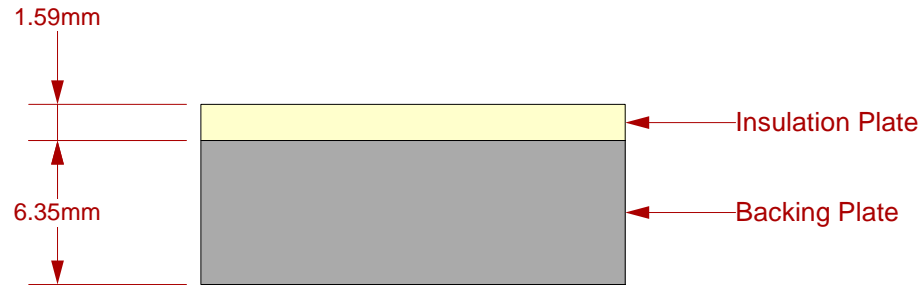
20 x 20 array

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	Drawing: H. Hansen	Date: 6/17/05		
	File: SG-BGA-7067 Dwg	Modified: 7/7/09, AE		


Top View



Side View



Description: Insulation Plate and Backing Plate

SG-BGA-7067 Drawing		Status: Released	Scale: 3:1	Rev: C
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			Date: 6/17/05	
			Modified: 7/7/09, AE	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)